

élantec
HIGH PERFORMANCE ANALOG INTEGRATED CIRCUITS

EL7262C/EL7272C

Dual Channel, High Speed, Power MOSFET w/Isolated Drains

Features

- Separate drain connections
- 3V and 5V Input compatible
- Clocking speeds up to 10 MHz
- 20 ns Switching/delay time
- 2A Peak drive
- Low output impedance
- Low quiescent current
- Wide operating voltage

Applications

- Asymmetrical switching
- Cascoded switching
- Resonant charging
- Floating load circuits
- Bridge circuits

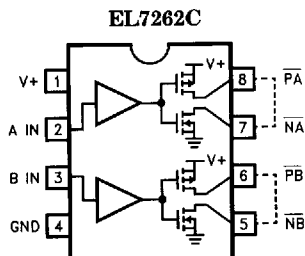
Ordering Information

Part No.	Temp. Range	Pkg.	Outline #
EL7262CN	-40°C to +85°C	8-Pin P-DIP	MDP0031
EL7262CS	-40°C to +85°C	8-Pin SO	MDP0027
EL7272CN	-40°C to +85°C	8-Pin P-DIP	MDP0031
EL7272CS	-40°C to +85°C	8-Pin SO	MDP0027

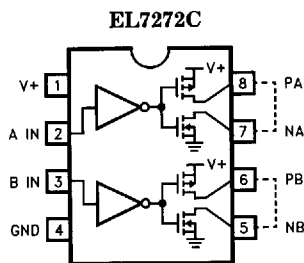
General Description

The EL7262C/EL7272C, dual channel, power MOSFET drivers achieve the same excellent switching performance of the EL7202 family, with the added flexibility derived through the isolated drain architecture. The outputs can be configured in numerous ways, depending upon the application. The EL7262C and EL7272C are available in 8-pin P-DIP and 8-lead SO packages.

Connection Diagrams



7262-1



7262-2

Manufactured under U.S. Patent Nos. 5,334,883, #5,341,047

EL7262C/EL7272C**Dual Channel, High Speed, Power MOSFET w/Isolated Drains****Absolute Maximum Ratings**

Supply (V+ to Gnd)	16.5V	Operating Junction Temperature	125°C
Input Pins	-0.3V to +0.3V above V+	Power Dissipation	
Combined Peak Output Current	4A	SOIC	570 mW
Storage Temperature Range	-65°C to +150°C	PDIP	1050 mW
Ambient Operating Temperature	-40°C to +85°C		

Important Note:

All parameters having Min/Max specifications are guaranteed. The Test Level column indicates the specific device testing actually performed during production and Quality inspection. Elantec performs most electrical tests using modern high-speed automatic test equipment, specifically the LTX77 Series system. Unless otherwise noted, all tests are pulsed tests, therefore $T_J = T_C = T_A$.

Test Level	Test Procedure
I	100% production tested and QA sample tested per QA test plan QCX0002.
II	100% production tested at $T_A = 25^\circ\text{C}$ and QA sample tested at $T_A = 25^\circ\text{C}$, T_{MAX} and T_{MIN} per QA test plan QCX0002.
III	QA sample tested per QA test plan QCX0002.
IV	Parameter is guaranteed (but not tested) by Design and Characterization Data.
V	Parameter is typical value at $T_A = 25^\circ\text{C}$ for information purposes only.

DC Electrical Characteristics $T_A = 25^\circ\text{C}$, $V = 15\text{V}$ unless otherwise specified

Parameter	Description	Test Conditions	Min	Typ	Max	Test Level	Units
Input							
V_{IH}	Logic "1" Input Voltage		2.4			I	V
I_{IH}	Logic "1" Input Current	@V+		0.1	10	I	μA
V_{IL}	Logic "0" Input Voltage				0.8	I	V
I_{IL}	Logic "0" Input Current	@0V		0.1	10	I	μA
V_{HVS}	Input Hysteresis			0.3		V	V
Output							
R_{OH}	Pull-Up Resistance	$I_{OUT} = -100\text{ mA}$		3	6	I	Ω
R_{OL}	Pull-Down Resistance	$I_{OUT} = +100\text{ mA}$		4	6	I	Ω
I_{OFF}	Output Leakage	$V_{OUT} = V+$ $V_{OUT} = 0\text{V}$		0.2	10	I	μA
I_{PK}	Peak Output Current	Source Sink		2 2		IV	A
I_{DC}	Continuous Output Current	Source/Sink	100			I	mA
Power Supply							
I_S	Power Supply Current	Inputs EL7262 High EL7272		1 4.5	2.5 7.5	I	mA
V_S	Operating Voltage		4.5		16	I	V

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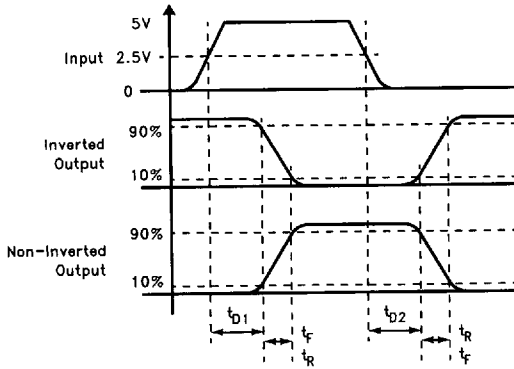
EL7262C/EL7272C

Dual Channel, High Speed, Power MOSFET w/Isolated Drains

AC Electrical Characteristics $T_A = 25^\circ\text{C}$, $V = 15\text{V}$ unless otherwise specified

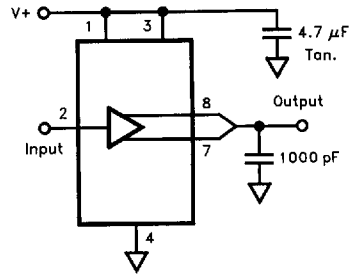
Parameter	Description	Test Conditions	Min	Typ	Max	Test Level	Units
Switching Characteristics							
t_R	Rise Time	$C_L = 500\text{ pF}$ $C_L = 1000\text{ pF}$		7.5 10	20	IV	ns
t_F	Fall Time	$C_L = 500\text{ pF}$ $C_L = 1000\text{ pF}$		10 13	20	IV	ns
t_{D-ON}	Turn-On Delay Time	See Timing Table		18	25	IV	ns
t_{D-OFF}	Turn-Off Delay Time	See Timing Table		20	25	IV	ns

Timing Table



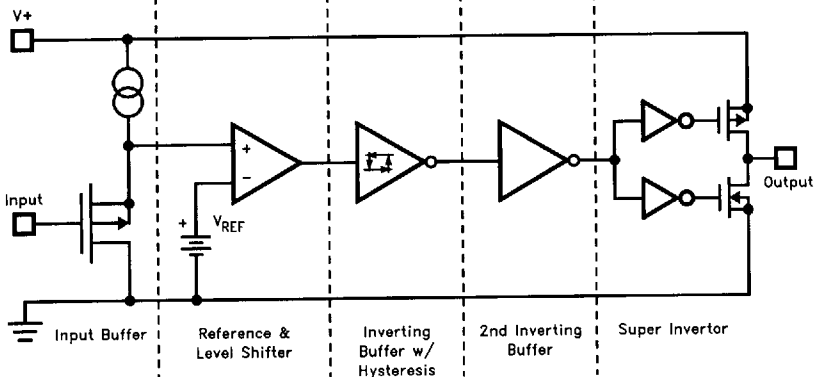
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Standard Test Configuration



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Simplified Schematic



7262-5

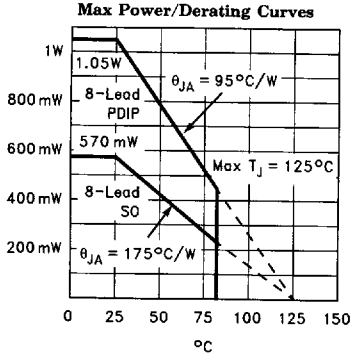
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EL7262C/EL7272C

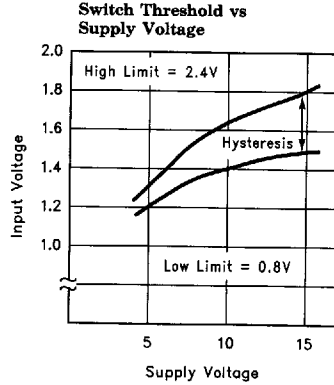
Dual Channel, High Speed, Power MOSFET w/Isolated Drains

EL7262C/EL7272C

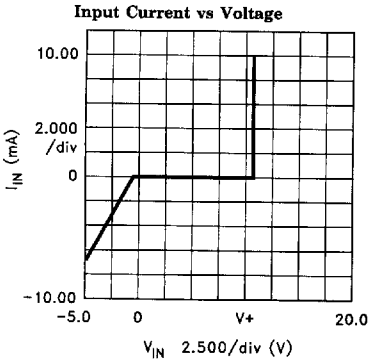
Typical Performance Curve



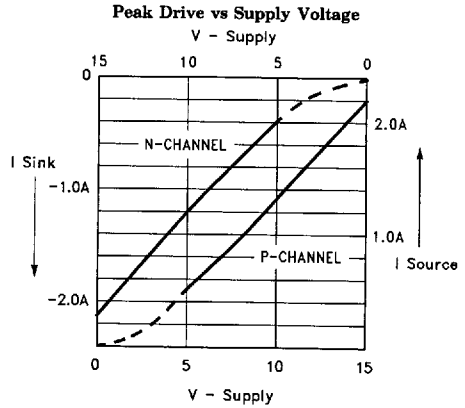
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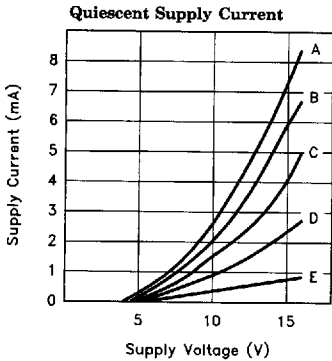
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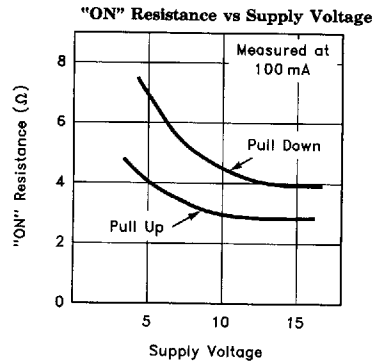


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CASE:

Device	Input Level	Curve
EL7262	GND	C
EL7262	GND, V+	D
EL7262	V+	E
EL7272	GND	A
EL7272	GND, V+	B
EL7272	V+	C



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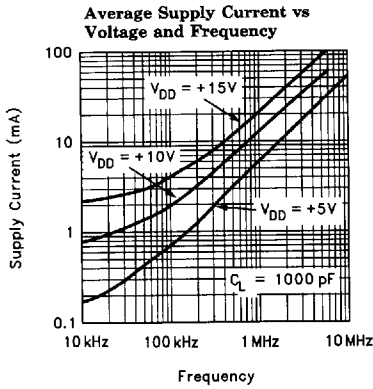
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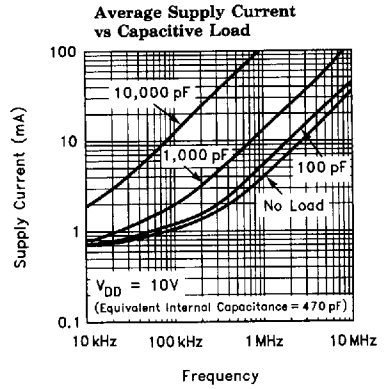
EL7262C/EL7272C

Dual Channel, High Speed, Power MOSFET w/Isolated Drains

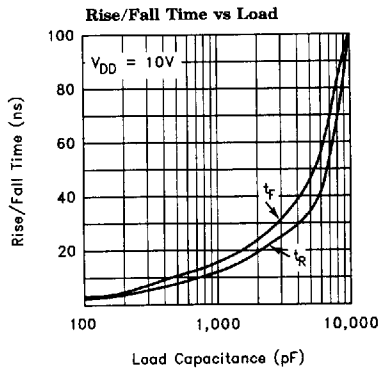
Typical Performance Curve — Contd.



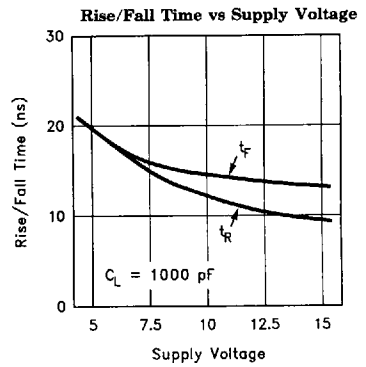
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7262-14



7262-11



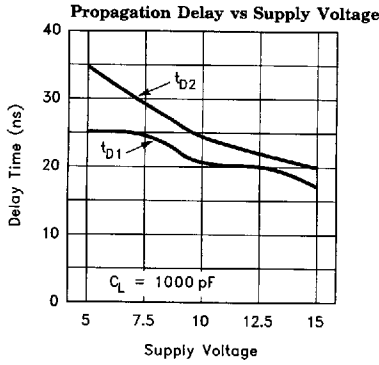
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EL7262C/EL7272C

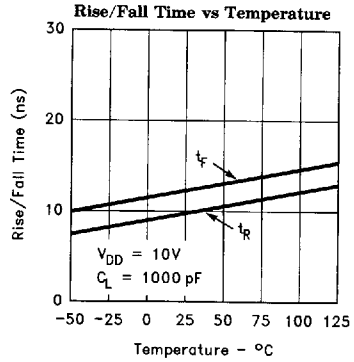
Dual Channel, High Speed, Power MOSFET w/Isolated Drains

EL7262C/EL7272C

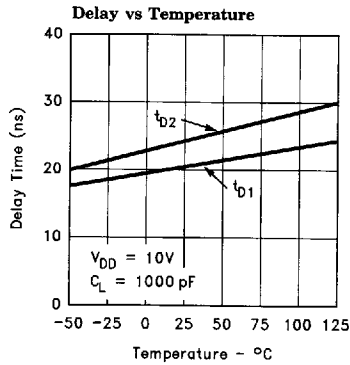
Typical Performance Curve — Contd.



7262-16



7262-17



7262-18

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Soldering Packages to PC Boards

DIP Packages

Wave soldering is recommended for DIP packages. Solder plated boards are recommended. Rosin mildly activated (RMA) flux is needed. Wave soldering using a dual wave system at $250^{\circ}\text{C} \pm 10^{\circ}\text{C}$ for two seconds per wave is preferable. Thorough cleaning of boards after soldering is required.

Hand soldering, Elantec's DIP packages will survive a peak temperature of 300°C (at leads) for a maximum period of 10 seconds.

Surface Mount Packages

Wave soldering and vapor phase or infrared (IR) reflow can be used for soldering surface mount packages to PC boards. Solder plated boards are recommended for wave soldering and vapor phase or IR reflow methods.

Wave Soldering: Adhesive is used to hold components on the boards during wave soldering. Place components on the board and cure adhesive

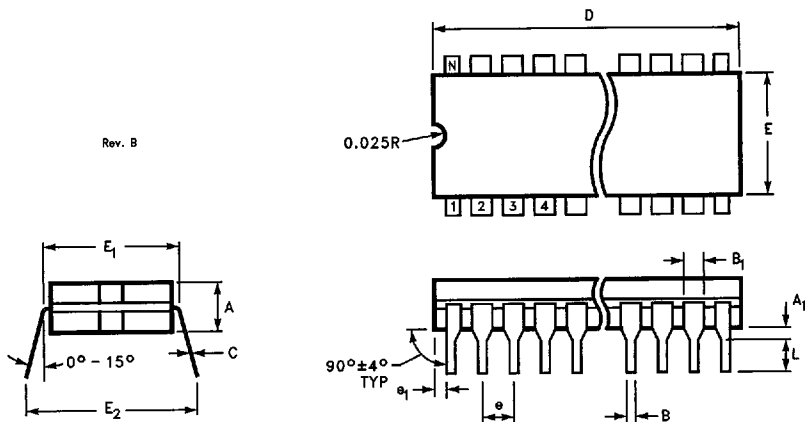
before wave soldering. Rosin mildly activated (RMA) flux or organic flux is needed. Wave soldering using a dual wave system at $250^{\circ}\text{C} \pm 10^{\circ}\text{C}$ for a maximum of two seconds per wave is preferable. Thorough cleaning of boards after soldering is required.

Reflow Soldering: Screen solder paste on board and attach components to board. Solder paste with RMA flux is recommended. Bake boards at 65°C – 90°C for 15 minutes. Preheat boards to within 60°C – 70°C of the solder temperature. To reflow solder paste with vapor phase method, the solder paste temperature must be maintained at or above 200°C for at least 30 seconds. The components temperature can not exceed 215°C . For the IR reflow method, the solder paste temperature must be maintained at or above 200°C for at least 30 seconds. The components temperature can not exceed 220°C . The temperature/time ramp-up during vapor phase or IR reflow shall be no greater than $2^{\circ}\text{C}/\text{sec}$.

Hand soldering, Elantec's surface mount packages will survive a peak temperature of 260°C (at leads) for a maximum period of 10 seconds.

Package Outlines

Rev. B



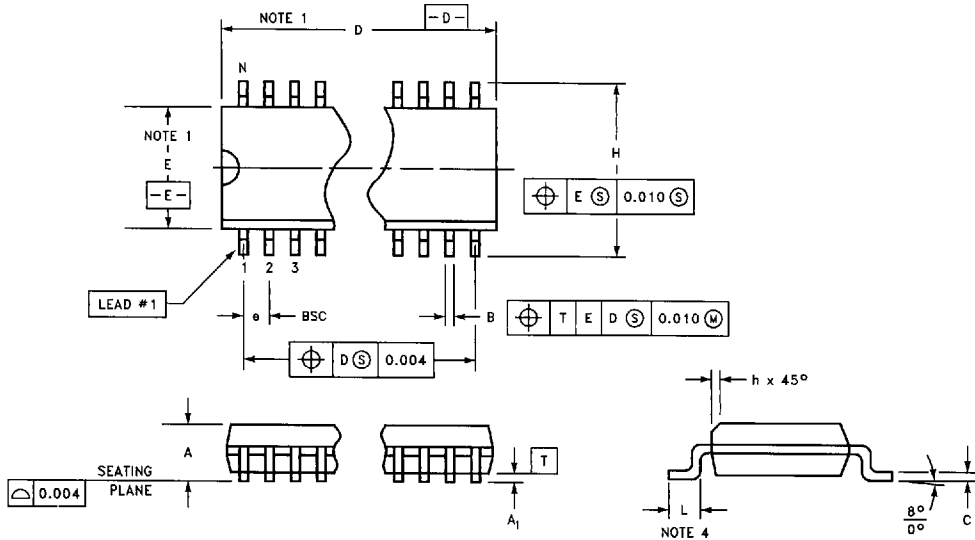
MDP0016 Rev. B

CerDIP Package

Lead Finish (Coml)—Tin Plate or Hot Solder DIP

Lead Finish (Mil)—Hot Solder DIP

Common Dimensions	Min	Max	Min	Max	Min	Max	Min	Max
A	0.140	0.160	0.140	0.160	0.140	0.160	0.140	0.160
A ₁	0.115	0.055	0.020	0.050	0.015	0.060	0.020	0.050
B	0.016	0.023	0.016	0.021	0.014	0.026	0.016	0.021
B ₁	0.050	0.065	0.050	0.060	0.038	0.068	0.050	0.060
C	0.008	0.012	0.008	0.012	0.008	0.018	0.008	0.012
D	0.375	0.395	0.760	0.785	0.940	0.960	1040.925	1.060
E	0.245	0.265	0.220	0.291	0.220	0.310	0.2780	0.298
E ₁	0.300	0.320	0.300	0.320	0.290	0.320	0.300	0.320
E ₂	0.340	0.390	0.340	0.390	0.360	0.410	0.340	0.390
e	0.090	0.110	0.090	0.110	0.090	0.110	0.090	0.110
e ₁	0.020	0.055	0.078	0.098	0.068	0.098	0.078	0.098
L	0.125	0.150	0.125	0.150	0.125	0.150	0.130	0.150
N	8-Lead		14-Lead		18-Lead		20-Lead	



REV. C

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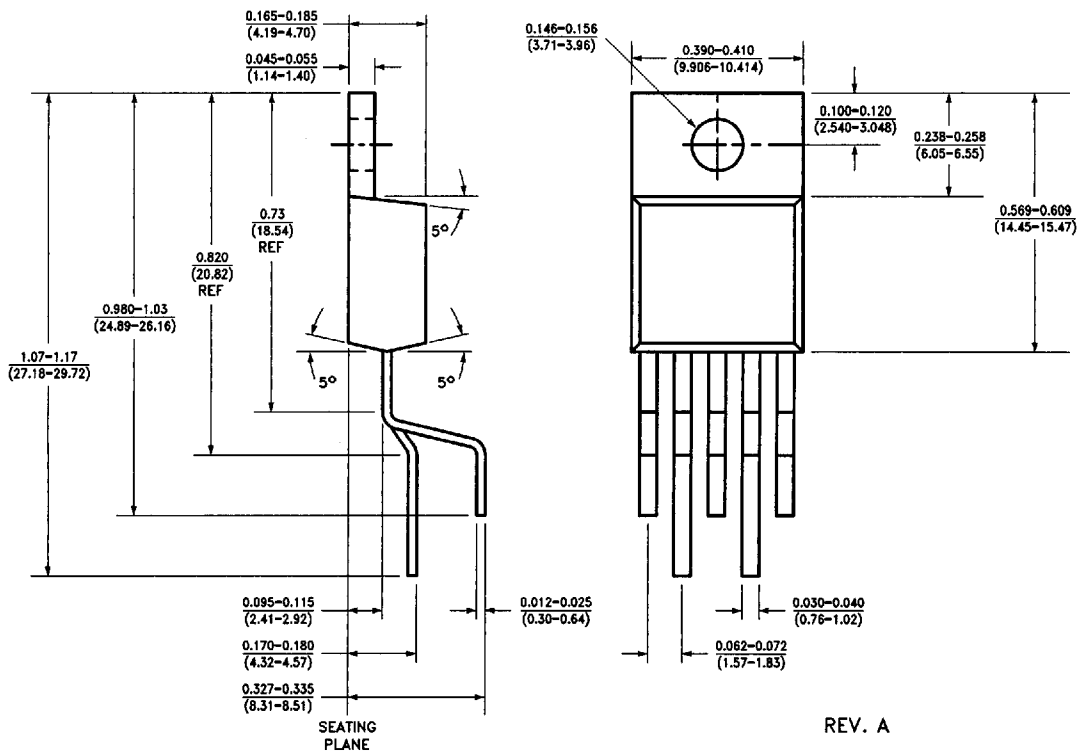
- Note 1: These dimensions do not include mold flash or protrusions. Mold flash protrusion shall not exceed .006" on any side.
- Note 2: SO-8, SO-14, SO-16 packages are narrow body (0.150").
- Note 3: Dimensions and tolerancing per ANSI Y14.5M-1982.
- Note 4: Flat area of lead foot.
- Note 5: SOL-24T2 (thermal package) has 2 fused leads on each side of package.
- Note 6: SOL-20T (thermal package) has 4 fused leads on each side of package.
- Note 7: SOL-28T contains a thermal metal slug.

MDP0027 Rev. C
Package Outline—SOIC
 Lead Finish—Solder Plate

Symbol	Lead Count													
	SOL-28		SOL-20		SOL-16		SO-16		SO-14		SO-8		SOL-24	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
A	0.096	0.104	0.096	0.104	0.096	0.104	0.061	0.068	0.061	0.068	0.061	0.068	0.096	0.104
A ₁	0.004	0.011	0.004	0.011	0.004	0.011	0.004	0.010	0.004	0.010	0.004	0.010	0.004	0.011
B	0.014	0.019	0.014	0.019	0.014	0.019	0.014	0.019	0.014	0.019	0.014	0.019	0.014	0.019
C	0.009	0.012	0.009	0.012	0.009	0.012	0.008	0.010	0.008	0.010	0.008	0.010	0.009	0.012
D	0.696	0.712	0.498	0.510	0.397	0.430	0.386	0.394	0.337	0.344	0.189	0.196	0.598	0.614
E	0.291	0.299	0.291	0.299	0.291	0.299	0.150	0.157	0.150	0.157	0.150	0.157	0.291	0.299
e	0.050 BSC		0.050 BSC		0.050 BSC		0.050 BSC		0.050 BSC		0.050 BSC		0.050 BSC	
H	0.398	0.414	0.398	0.414	0.398	0.414	0.230	0.244	0.230	0.244	0.230	0.244	0.398	0.414
h	0.010	0.016	0.010	0.016	0.010	0.016	0.010	0.016	0.010	0.016	0.010	0.016	0.010	0.016
L	0.016	0.024	0.016	0.024	0.016	0.024	0.016	0.024	0.016	0.024	0.016	0.024	0.016	0.024

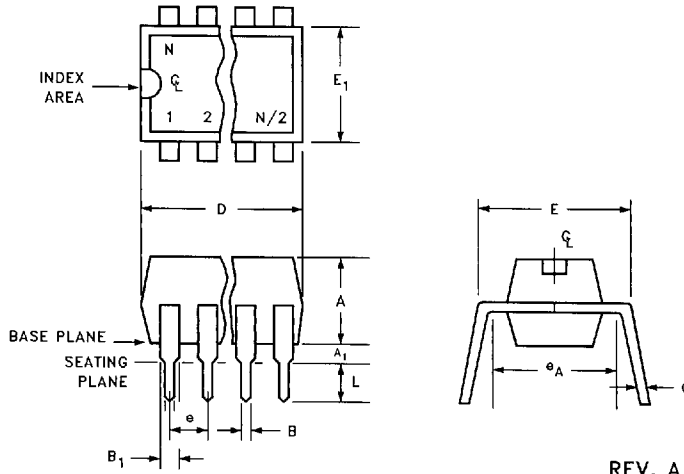
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Package Outlines



MDP0028 Rev. A
5-Lead TO-220
 Lead Finish—Solder Plate

REV. A



REV. A

MDP0031 Rev. A
Plastic Package
Lead Finish—Hot Solder DIP

Common Dimensions	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
A ₁	0.020	0.040	0.020	0.040	0.020	0.040	0.020	0.040	0.020	0.040
A	0.125	0.145	0.125	0.145	0.125	0.145	0.125	0.145	0.125	0.145
B	0.016	0.020	0.016	0.020	0.016	0.020	0.016	0.020	0.015	0.021
B ₁	0.050	0.070	0.050	0.070	0.050	0.070	0.050	0.070	0.050	0.070
C	0.008	0.012	0.008	0.012	0.008	0.012	0.008	0.012	0.008	0.012
D	0.350	0.385	0.745	0.755	0.745	0.755	0.875	0.905	0.925	1.045
E	0.295	0.320	0.295	0.320	0.295	0.320	0.295	0.320	0.295	0.320
E ₁	0.245	0.255	0.245	0.255	0.245	0.255	0.245	0.255	0.245	0.255
e	0.100 Typ		0.100 Typ		0.100 Typ		0.100 Typ		0.100 Typ	
e _A	0.300 Ref		0.300 Ref		0.300 Ref		0.300 Ref		0.300 Ref	
L	0.115	0.135	0.115	0.135	0.115	0.135	0.115	0.135	0.115	0.135
N	8		14		16		18		20	

Note: Package outline exclusive of any mold flashes. Mold flash protrusion shall not exceed 0.006" on any side.